DATA SHEET



GaAs HBT INTEGRATED CIRCUIT

μ PG2318T5N

2.4 GHz SINGLE BAND POWER AMPLIFIER FOR W-LAN

DESCRIPTION

The μ PG2318T5N is a GaAs HBT MMIC power amplifier for 2.4 GHz band wireless LAN.

This device realizes high efficiency, high gain and high output power by using InGaP HBT.

This device is housed in a 6-pin plastic TSON (Thin Small Out-line Non-leaded) package, and is suitable for high-density surface mounting.

FEATURES

Operating frequency : f_{opt} = 2 400 to 2 500 MHz (2 450 MHz TYP.)

Supply voltage : Vcc1, 2 = 3.0 to 4.6 V (3.3 V TYP.)
 Control voltage : Venable = 0 to 3.0 V (2.8 V TYP.)

• Circuit current : lcc = 120 mA TYP. @ Vcc1, 2 = 3.3 V, Venable = 2.8 V,

Pout = +18 dBm (at OFDM modulation : 64QAM/54 Mbps)

Power gain
 : GP = 28 dB TYP. @ Vcc1, 2 = 3.3 V, Venable = 2.8 V,

Pout = +18 dBm (at OFDM modulation : 64QAM/54 Mbps)

• Gain flatness : $\triangle GP = 0.8 \text{ dB TYP}$. @ f = 2.4 to 2.5 GHz, Vcc1, 2 = 3.3 V, Venable = 2.8 V,

Pout = +18 dBm (at OFDM modulation : 64QAM/54 Mbps)

Error vector magnitude : EVM = 2.5% TYP. @ Vcc1, 2 = 3.3 V, Venable = 2.8 V,

Pout = +18 dBm (at OFDM modulation : 64QAM/54 Mbps)

• Harmonics : 2f0 = 30 dBc TYP. @ Vcc1, 2 = 3.3 V, Venable = 2.8 V,

Pout = +18 dBm (at OFDM modulation : 64QAM/54 Mbps)

High-density surface mounting: 6-pin plastic TSON package (1.5 x 1.5 x 0.37 mm)

APPLICATIONS

- Power Amplifier for 802.11b/g
- · 2.4 GHz ISM Band Transceivers

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2318T5N-E2	μPG2318T5N-E2-A	6-pin plastic TSON (Pb-Free)	G5G	Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

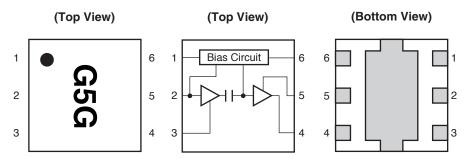
Part number for sample order: μ PG2318T5N-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	Venable
2	INPUT
3	Vcc1
4	OUTPUT
5	Vcc2
6	V _{det}

Remark Exposed pad : GND

ABSOLUTE MAXIMUM RATINGS (Ta = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	Vcc1, 2	5.0	V
Control Voltage	Venable	4.0	V
Input Power	Pin	+10	dBm
Power Dissipation	Po	500 ^{Note}	mW
Operating Ambient Temperature	Та	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, TA = +85°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	fopt	2 400	2 450	2 500	MHz
Supply Voltage	Vcc1, 2	3.0	3.3	4.6	V
Control Voltage	Venable	0	2.8	3.0	V

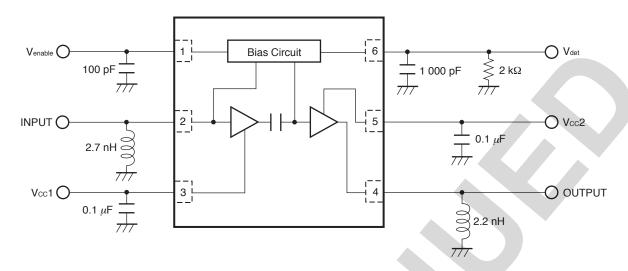
ELECTRICAL CHARACTERISTICS

 $(T_A = +25^{\circ}C, f = 2\ 400\ to\ 2\ 500\ MHz, OFDM\ modulation: 64QAM/54\ Mbps, Vcc1, 2 = 3.3\ V,$ $V_{enable} = 2.8\ V,$ external input and output matching, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	Icc	P _{out} = +18 dBm	-	120	140	mA
Power Gain	G₽	P _{out} = +18 dBm	25.5	28	-	dB
Gain Flatness	⊿Gp	P _{out} = +18 dBm	-	0.8	1.3	dB
Control Current	lenable	P _{out} = +18 dBm	-	3.2	<u>}</u>	mA
Error Vector Magnitude	EVM	P _{out} = +18 dBm		2.5	-	%
Input Return Loss	RLin	Pout = -30 dBm (no-modulation)	-	15	-	dB
Output Return Loss	RLout	Pout = -30 dBm (no-modulation)	-	5	_	dB
2nd Harmonics	2f0	Pout = +18 dBm	1	30	-	dBc
3rd Harmonics	3f0	Pout = +18 dBm	-	48	-	dBc
Power Detector Voltage	Vdet	Pout = +18 dBm	-	0.7	-	V



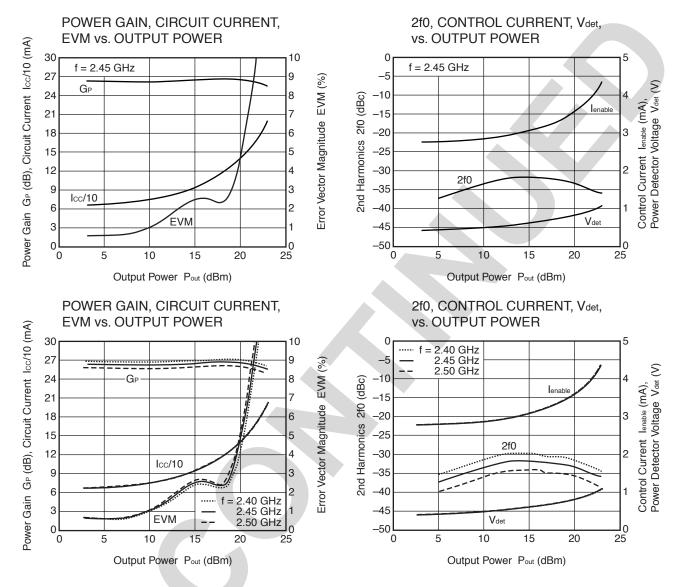
<R> EVALUATION CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

TYPICAL CHARACTERISTICS 1

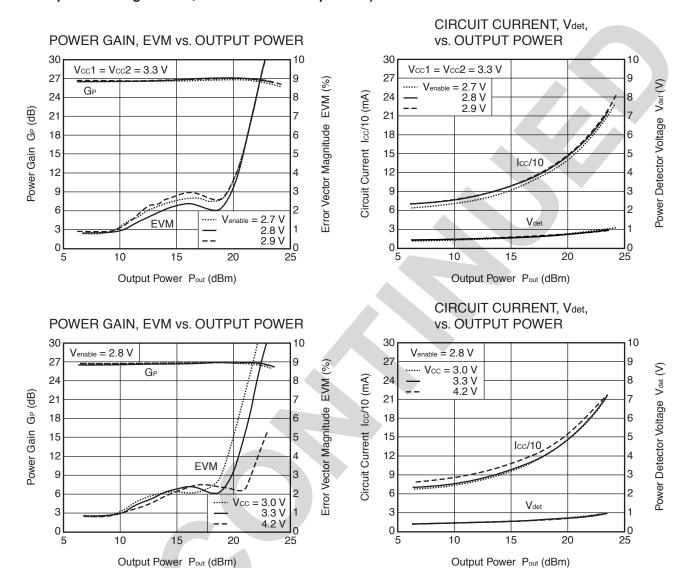
 $(T_A = +25^{\circ}C, V_{CC}1, 2 = 3.3 \text{ V}, V_{enable} = 2.8 \text{ V}, OFDM modulated signal : 64QAM/54 Mbps, with external input and output matching circuits, unless otherwise specified)$



Remark The graphs indicate nominal characteristics.

TYPICAL CHARACTERISTICS 2

 $(T_A = +25^{\circ}C, f = 2.45 \text{ GHz}, OFDM \text{ modulated signal} : 64QAM/54 \text{ Mbps}, with external input and output matching circuits, unless otherwise specified)$

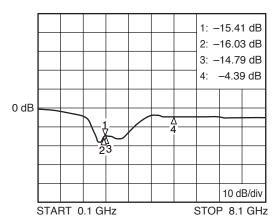


Remark The graphs indicate nominal characteristics.

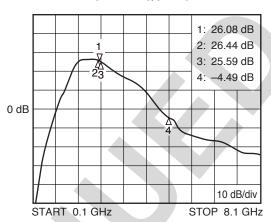
<R> S-PARAMETERS (Reference Data) -This data is included external matching components-

Condition : $T_A = +25^{\circ}C$, f = 0.1 to 8.1 GHz, V_{CC1} , Q = 3.3 V, $V_{enable} = 2.8$ V, $P_{in} = -30$ dBm

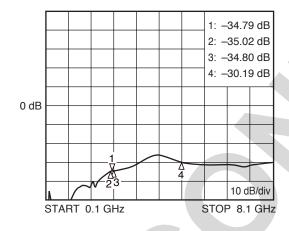
S₁₁-FREQUENCY



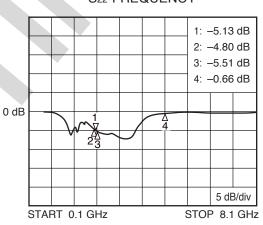
S21-FREQUENCY



S₁₂-FREQUENCY



S22-FREQUENCY



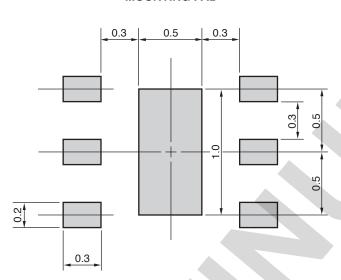
Remark 1. The graphs indicate nominal characteristics.

2. Marker1: 2.45 GHz Marker2: 2.40 GHz Marker3: 2.50 GHz Marker4: 4.90 GHz

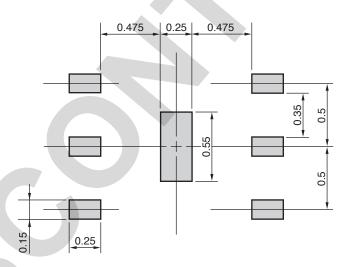
MOUNTING PAD AND SOLDER MASK LAYOUT DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)

MOUNTING PAD



SOLDER MASK

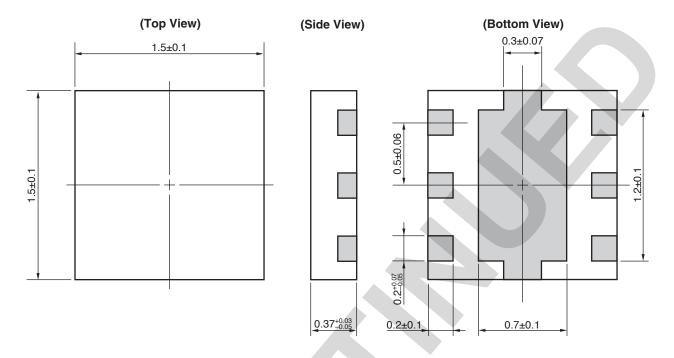


Solder thickness: 0.08 mm

Remark The mounting pad and solder mask layouts in this document are for reference only.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 - 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.





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This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not De	etected	
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
PBB	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

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